Preferred Device

# **General Purpose Transistor**

# **PNP Silicon**

#### **Features**

• Moisture Sensitivity Level: 1

• ESD Rating: – Human Body Model: > 4000 V

- Machine Model: > 400 V

• Pb-Free Package is Available

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Collector–Emitter Voltage	V <sub>CEO</sub>	-25	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	-25	Vdc
Emitter-Base Voltage	V <sub>EBO</sub>	-4	Vdc
Collector Current–Continuous	I <sub>C</sub>	-200	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (Note 1) @T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	225 1.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	556	°C/W
Total Device Dissipation Alumina Substrate, (Note 2) @T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	300 2.4	mW mW/°C
Thermal Resistance, Junction-to-Ambient (Note 2)	$R_{\theta JA}$	417	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

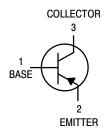
Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

- 1. FR-5 = 1.0  $\times$  0.75  $\times$  0.062 in. 2. Alumina = 0.4  $\times$  0.3  $\times$  0.024 in. 99.5% alumina.



# ON Semiconductor®

### http://onsemi.com





**CASE 318** STYLE 6

#### MARKING DIAGRAM



C3 = Device Code

M = Date Code\*

= Pb-Free Package

(Note: Microdot may be in either location) \*Date Code orientation and/or overbar may vary depending upon manufacturing location.

#### ORDERING INFORMATION

Device	Package	Shipping <sup>†</sup>		
MMBT4126LT1	SOT-23	3000/Tape & Reel		
MMBT4126LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

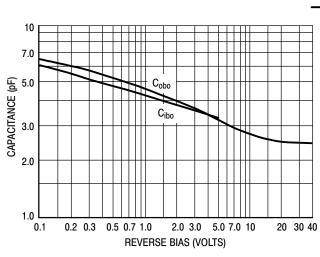
# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit	
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (Note 3) (I <sub>C</sub> = -1.0 mAdc, I <sub>B</sub> = 0)	V <sub>(BR)</sub> CEO	-25	_	Vdc	
Collector–Base Breakdown Voltage $(I_C = -10 \mu Adc, I_E = 0)$	V <sub>(BR)</sub> CBO	-25	_	Vdc	
Emitter–Base Breakdown Voltage $(I_E = -10 \mu Adc, I_C = 0)$	V <sub>(BR)EBO</sub>	-4	_	Vdc	
Collector Cutoff Current (V <sub>CE</sub> = -30 Vdc, V <sub>EB</sub> = -3.0 Vdc)	I <sub>CEX</sub>	_	-50	nAdc	
ON CHARACTERISTICS (Note 3)	•		•		
DC Current Gain	H <sub>FE</sub>	120 60	300	-	
Collector – Emitter Saturation Voltage ( $I_C = -50 \text{ mAdc}$ , $I_B = -5.0 \text{ mAdc}$ )	V <sub>CE(sat)</sub>	_	-0.4	Vdc	
Base – Emitter Saturation Voltage (I <sub>C</sub> = –50 mAdc, I <sub>B</sub> = –5.0 mAdc)	V <sub>BE(sat)</sub>	_	-0.95	Vdc	
SMALL-SIGNAL CHARACTERISTICS					
Current – Gain – Bandwidth Product (I <sub>C</sub> = –10 mAdc, V <sub>CE</sub> = –20 Vdc, f = 100 MHz)	f <sub>T</sub>	250	_	MHz	
Output Capacitance (V <sub>CB</sub> = -5.0 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>obo</sub>	_	4.5	pF	
Input Capacitance (V <sub>EB</sub> = -0.5 Vdc, I <sub>C</sub> = 0, f = 1.0 MHz)	C <sub>ibo</sub>	_	10	pF	
$\begin{aligned} & \text{Small} - \text{Signal Current Gain} \\ & \text{(I}_{\text{C}} = -2.0 \text{ mAdc, V}_{\text{CE}} = -10 \text{ Vdc, f} = 1.0 \text{ kHz)} \\ & \text{(I}_{\text{C}} = 10 \text{ mAdc, V}_{\text{CE}} = 20 \text{ Vdc, f} = 100 \text{ MHz)} \end{aligned}$	h <sub>fe</sub>	120 2.5	480 -	-	
Noise Figure (I <sub>C</sub> = $-100~\mu$ Adc, V <sub>CE</sub> = $-5.0~V$ dc, R <sub>S</sub> = $1.0~k\Omega$ , f = $1.0~kHz$ )	NF	_	4.0	dB	

<sup>3.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

# TYPICAL TRANSIENT CHARACTERISTICS

- T<sub>J</sub> = 25°C





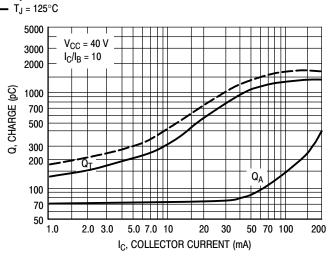
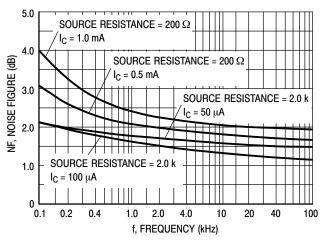


Figure 2. Charge Data

# TYPICAL AUDIO SMALL-SIGNAL CHARACTERISTICS NOISE FIGURE VARIATIONS

 $(V_{CE} = -5.0 \text{ Vdc}, T_A = 25^{\circ}\text{C}, Bandwidth = 1.0 \text{ Hz})$ 



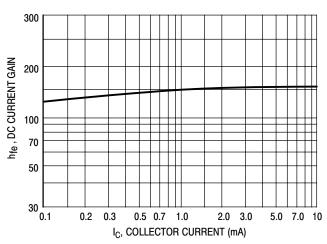
12 f = 1.0 kHz 10 NF, NOISE FIGURE (dB)  $I_C = 50 \mu A$  $I_C = 100 \mu A$ 2 0.2 2.0 10 20 40 0.1 1.0 4.0 100 Rg, SOURCE RESISTANCE (k OHMS)

Figure 3.

Figure 4.

#### h PARAMETERS

 $(V_{CE} = -10 \text{ Vdc}, f = 1.0 \text{ kHz}, T_A = 25^{\circ}\text{C})$ 



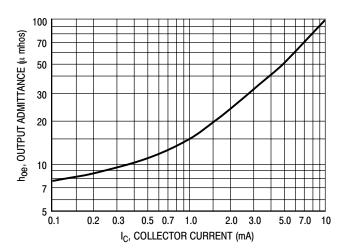
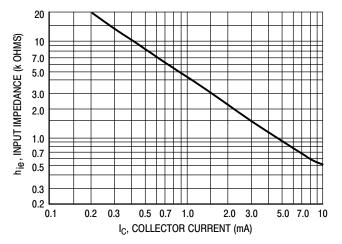


Figure 5. Current Gain

Figure 6. Output Admittance



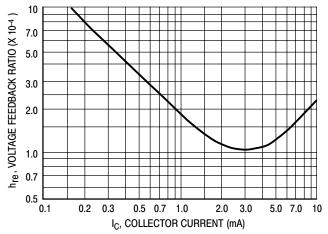


Figure 7. Input Impedance

Figure 8. Voltage Feedback Ratio

#### **TYPICAL STATIC CHARACTERISTICS**

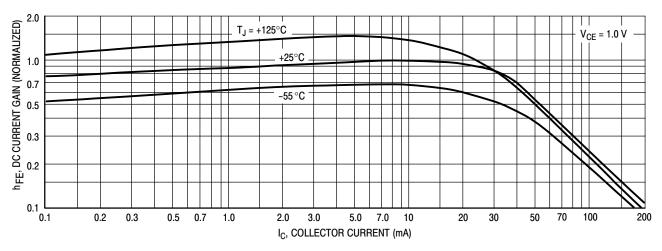


Figure 9. DC Current Gain

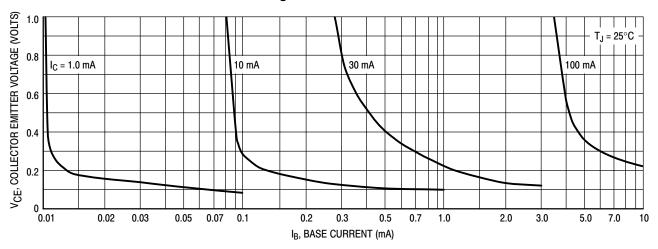


Figure 10. Collector Saturation Region

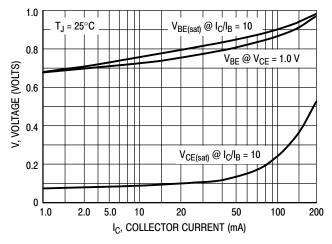


Figure 11. "ON" Voltages

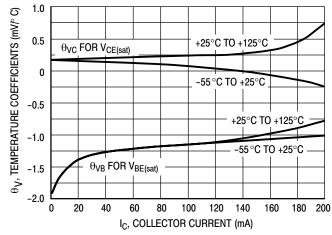
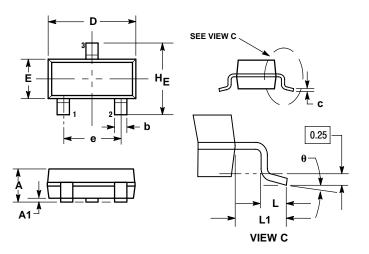


Figure 12. Temperature Coefficients

#### PACKAGE DIMENSIONS

SOT-23 (TO-236) CASE 318-08 **ISSUE AN** 



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER

  - ANSI Y14.5M, 1982.

    2. CONTROLLING DIMENSION: INCH.

    3. MAXIMUM LEAD THICKNESS INCLUDES
    LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF
  - BASE MATERIAL.

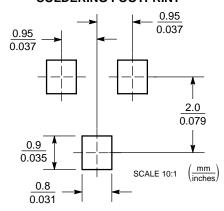
    3. 318-01 THRU -07 AND -09 OBSOLETE,
    NEW STANDARD 318-08.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
C	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
Е	1.20	1.30	1.40	0.047	0.051	0.055
ө	1.78	1.90	2.04	0.070	0.075	0.081
٦	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
He	2.10	2.40	2.64	0.083	0.094	0.104

#### STYLE 6:

- PIN 1. BASE 2. EMITTER COLLECTOR

# **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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